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(12) **United States Design Patent**
Takamoto et al.

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(45) **Date of Patent: ** Mar. 31, 2009**

(54) **ADHESIVE FILM MATERIAL FOR USE IN MANUFACTURING SEMICONDUCTORS**

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(73) Assignee: **Nitto Denko Corporation**, Osaka (JP)

(**) Term: **14 Years**

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(22) Filed: **Nov. 30, 2007**

(30) **Foreign Application Priority Data**

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May 30, 2007	(JP)	....	2007-014405
May 30, 2007	(JP)	....	2007-014407

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182; 29/25.35; 156/235, 248, 678; 257/678, E21.505; 310/340, 366; 438/133, 199, 450, 462
See application file for complete search history.

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Primary Examiner—Selina Sikder

(74) *Attorney, Agent, or Firm*—Osha • Liang LLP

(57) **CLAIM**

The ornamental design for adhesive film material for use in manufacturing semiconductors, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a first embodiment of the adhesive film material for use in manufacturing semiconductors showing our new design;

FIG. **2** is a front view thereof;

FIG. **3** is a plan view thereof;

FIG. **4** is a right side view, the left side being a mirror image thereof;

FIG. **5** is an enlarged plan view of the design as identified by A and B in FIG. **2**;

FIG. **6** is a sectional view taken along line **6**—**6** in FIG. **5**;

FIG. **7** is a sectional view taken along line **7**—**7** in FIG. **5**;

FIG. **8** is a perspective view of a second embodiment of the adhesive film material for use in manufacturing semiconductors;

FIG. **9** is a front view thereof;

FIG. **10** is a plan view thereof;

FIG. **11** is a right side view, the left side being a mirror image thereof;

FIG. **12** is an enlarged plan view of the design as identified by A and B in FIG. **9**;

FIG. **13** is a sectional view taken along line **13**—**13** in FIG. **12**;

FIG. **14** is a sectional view taken along line **14**—**14** in FIG. **12**;

FIG. **15** is a perspective view of a third embodiment of the adhesive film material for use in manufacturing semiconductors;

FIG. **16** is a front view thereof;

FIG. **17** is a plan view thereof;

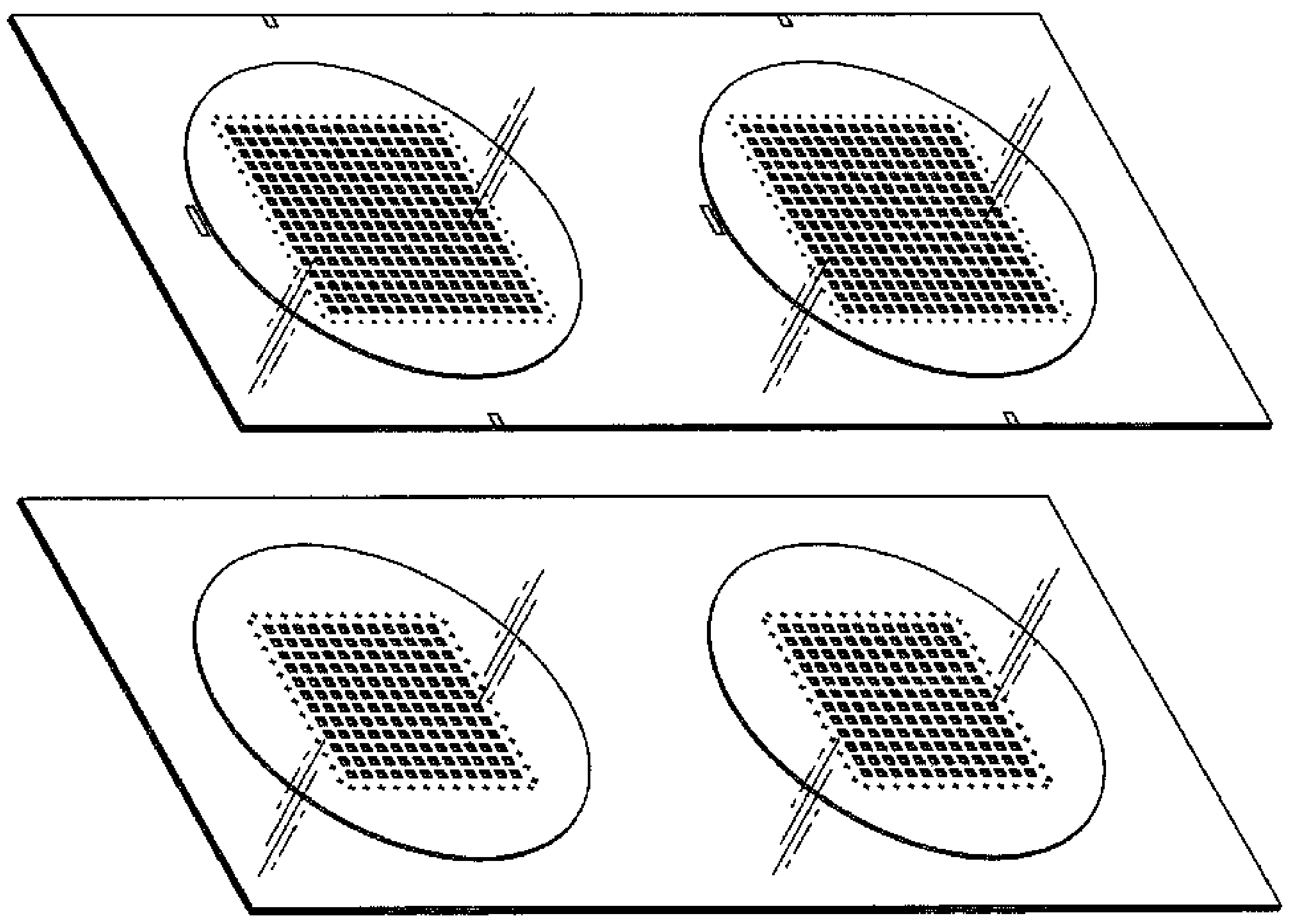
FIG. **18** is a right side view, the left side being a mirror image thereof;

FIG. **19** is an enlarged plan view of the design as identified by A and B in FIG. **16**;

FIG. **20** is a sectional view taken along line **20**—**20** in FIG. **19**; and,

FIG. **21** is a sectional view taken along line **21**—**21** in FIG. **19**.

1 Claim, 9 Drawing Sheets



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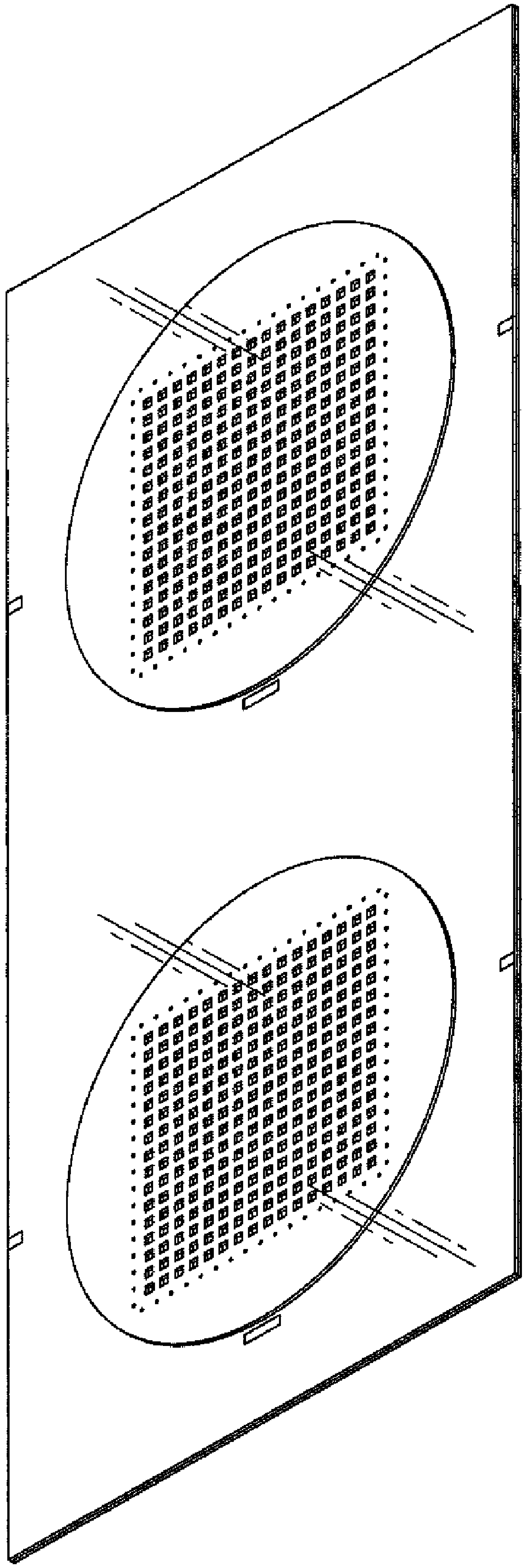

FIG. 1

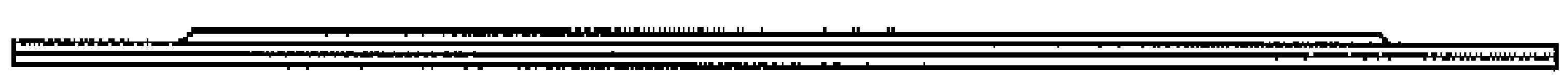

FIG. 4

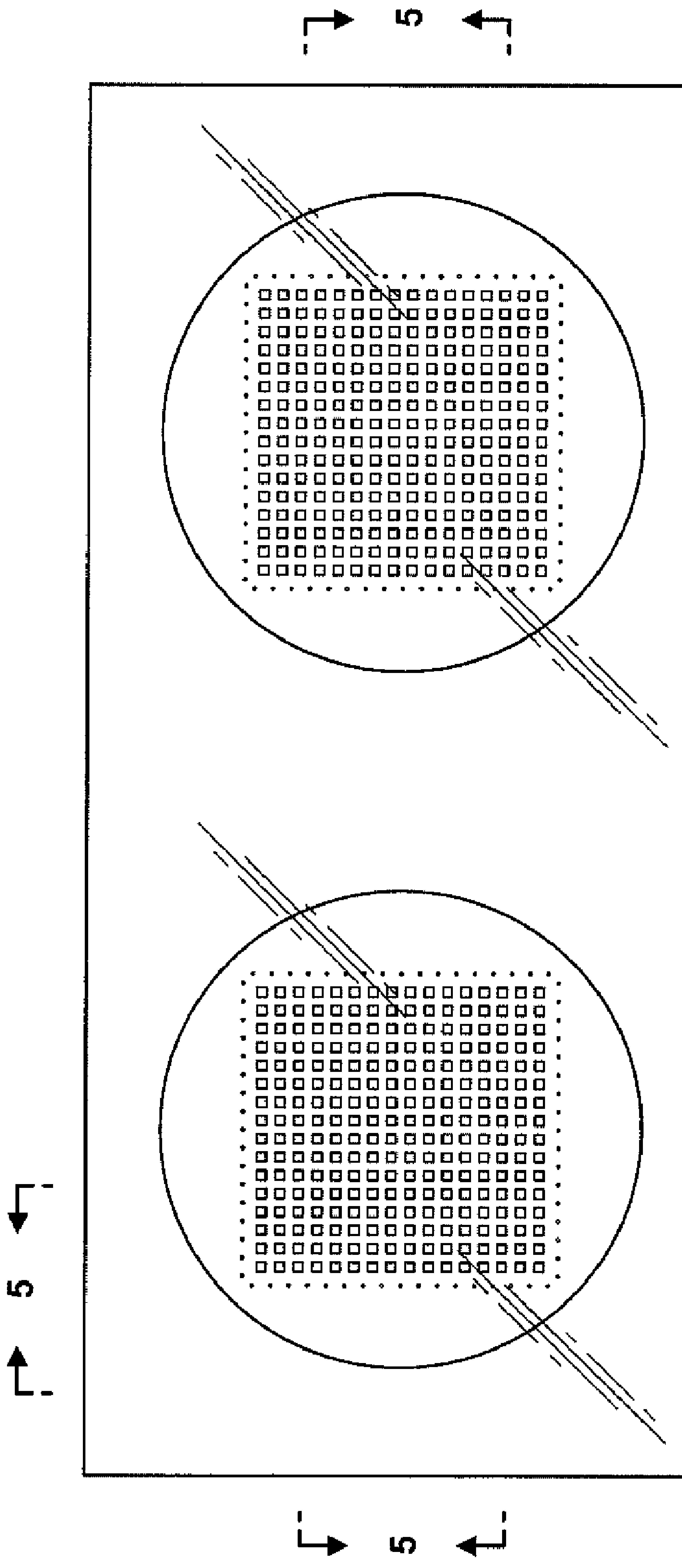

FIG. 2

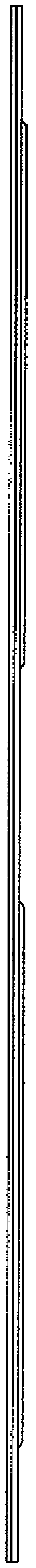

FIG. 3

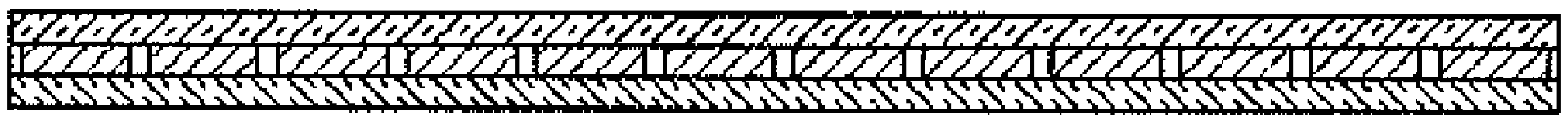

FIG. 7

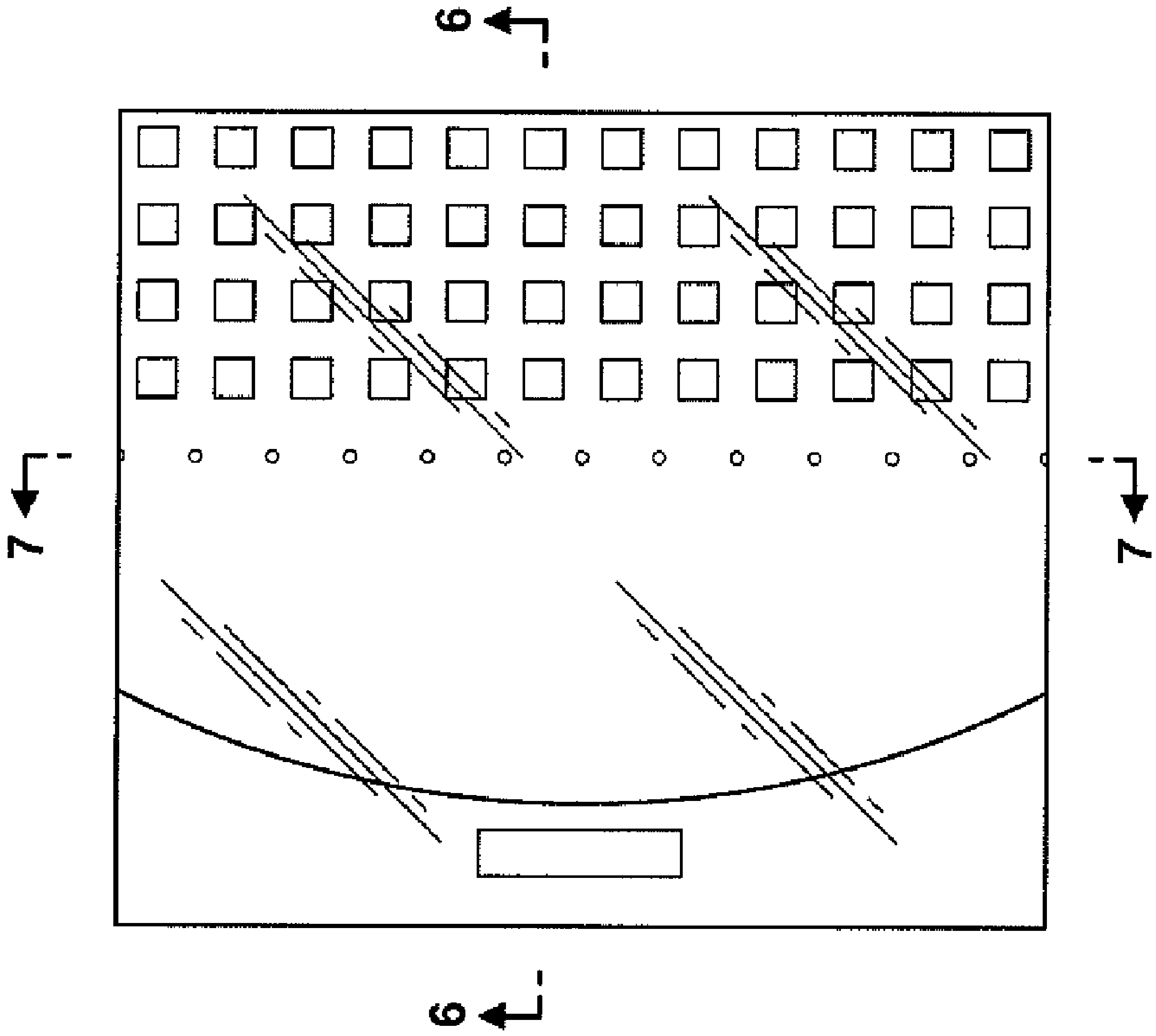

FIG. 5

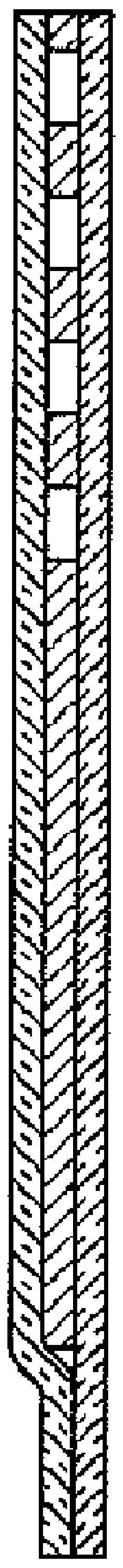

FIG. 6

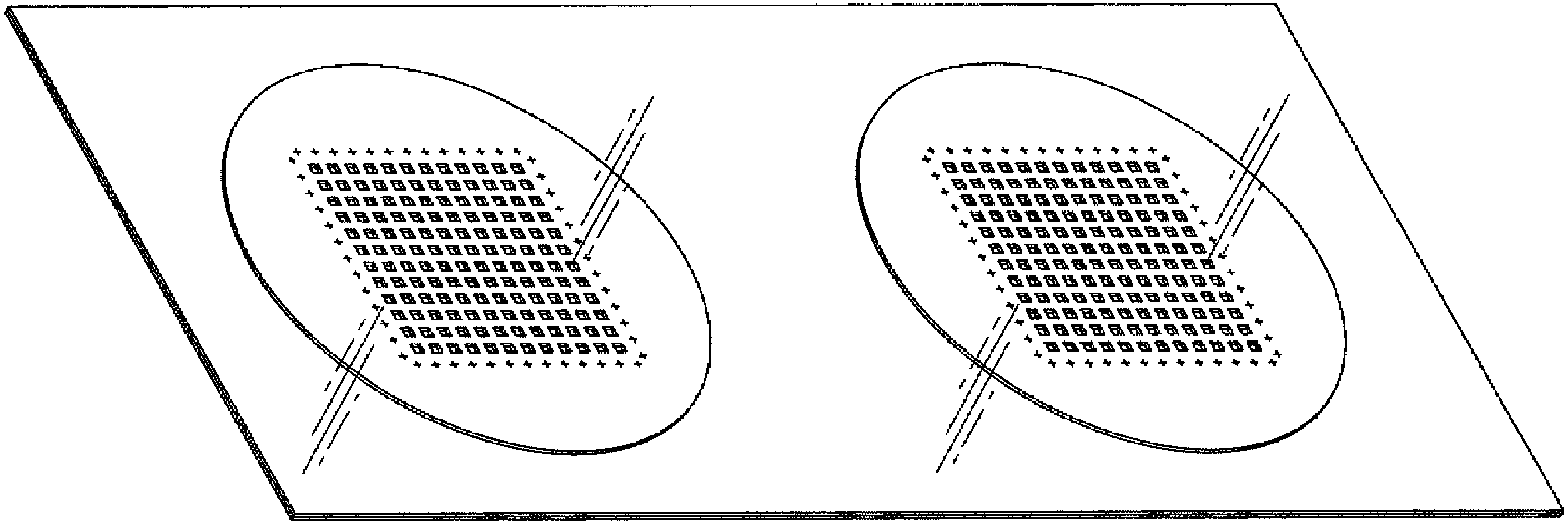

FIG. 8

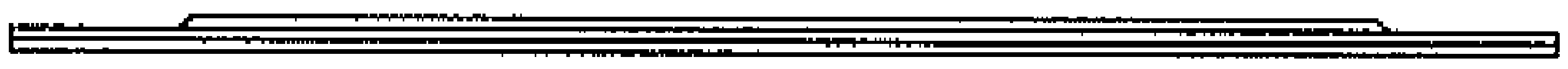

FIG. 11

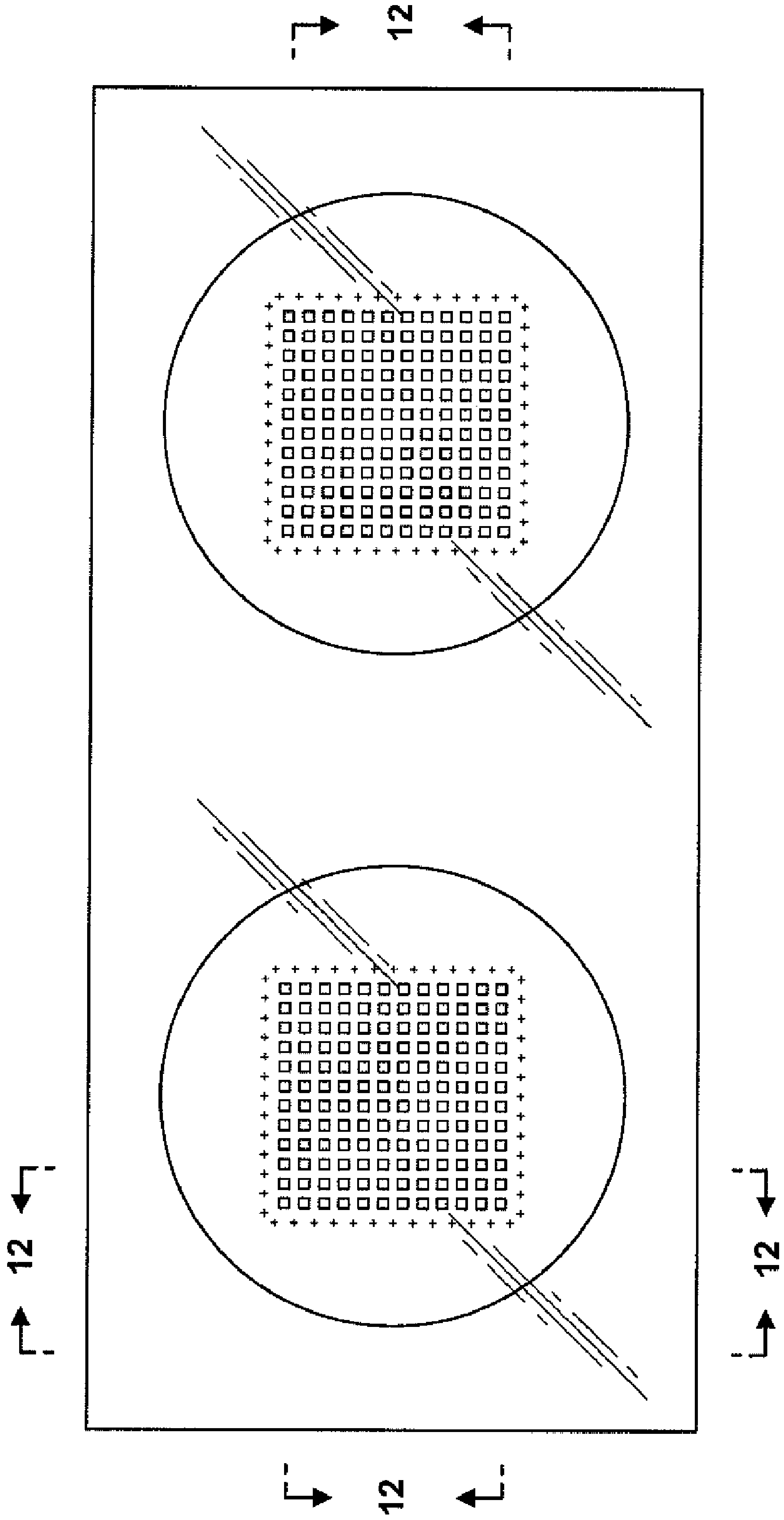

FIG. 9

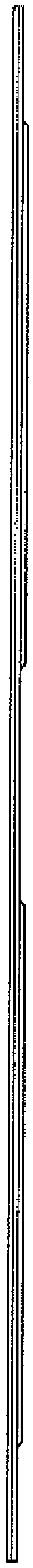

FIG. 10

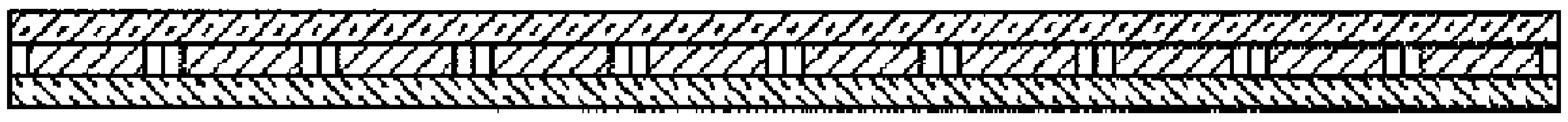

FIG. 14

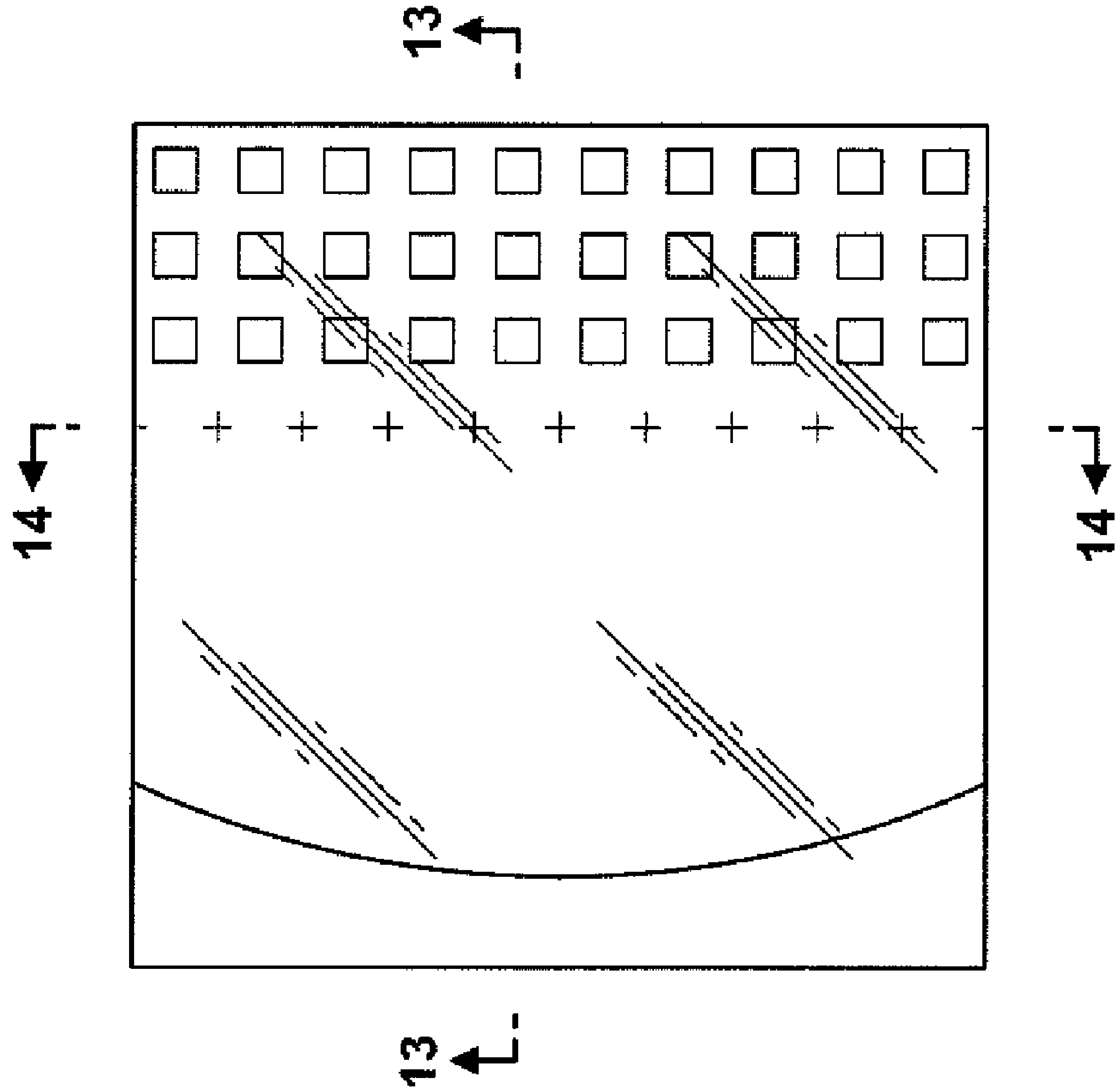

FIG. 12

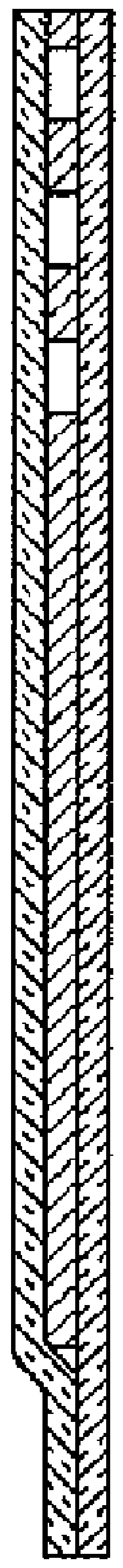

FIG. 13

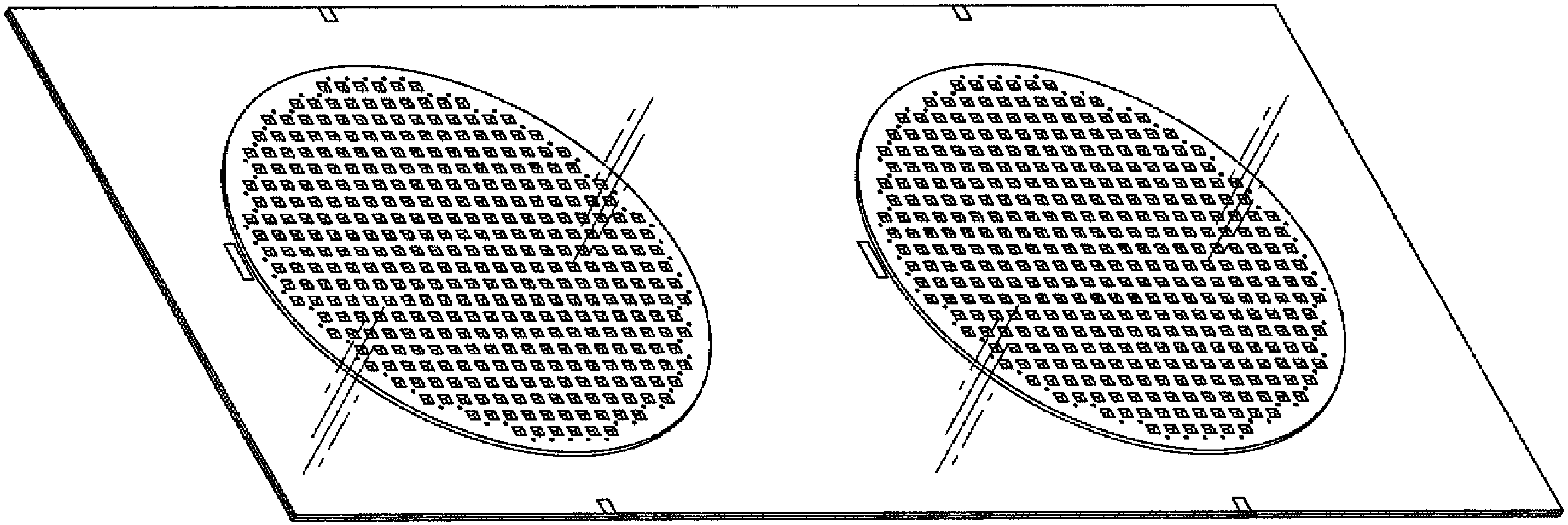

FIG. 15

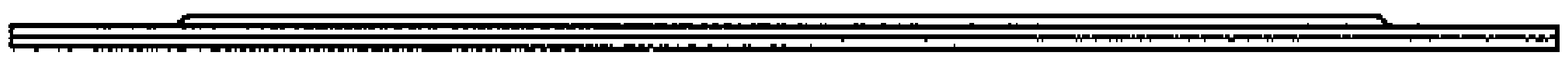

FIG. 18

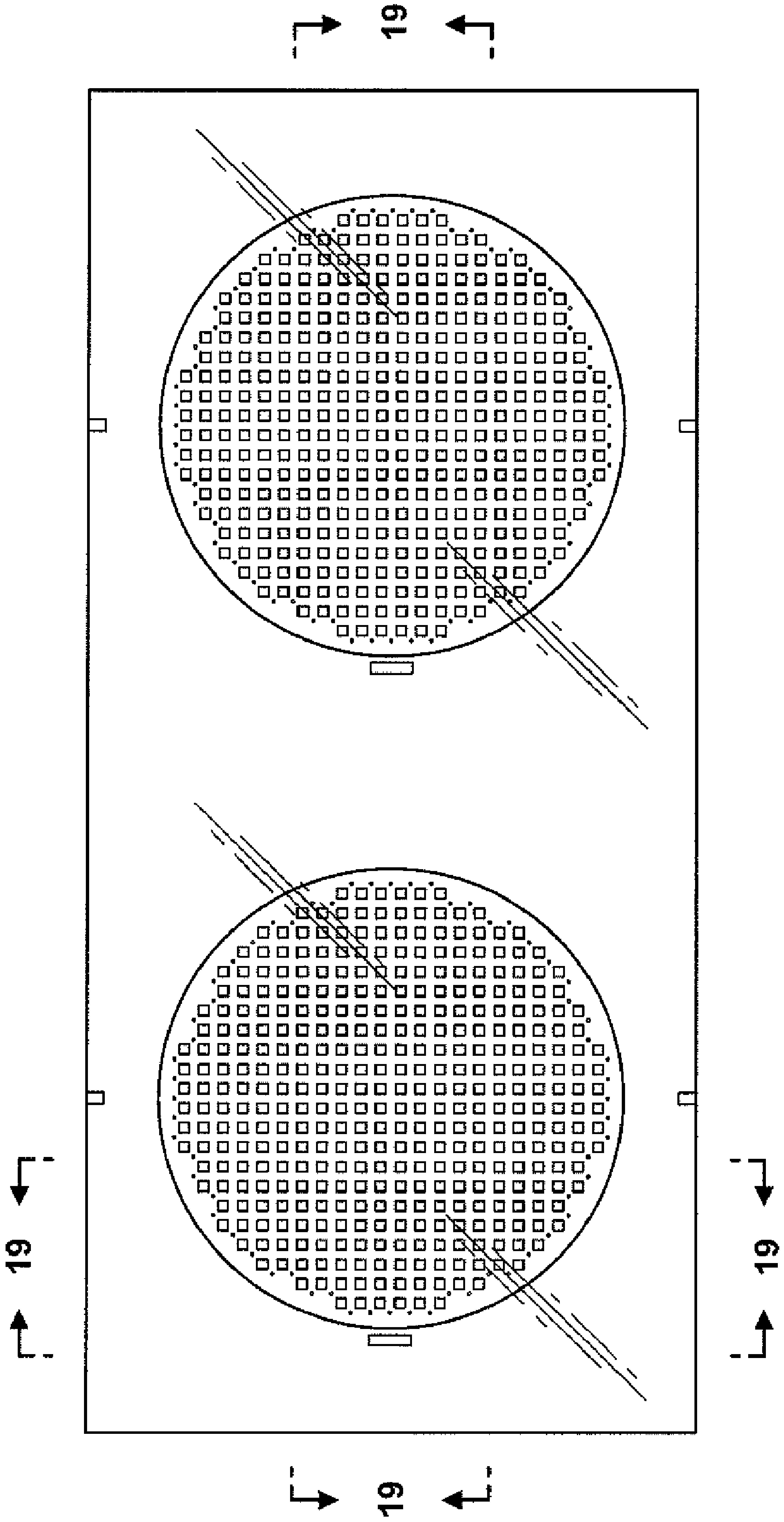

FIG. 16

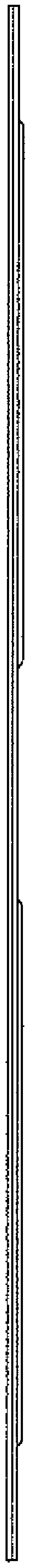

FIG. 17

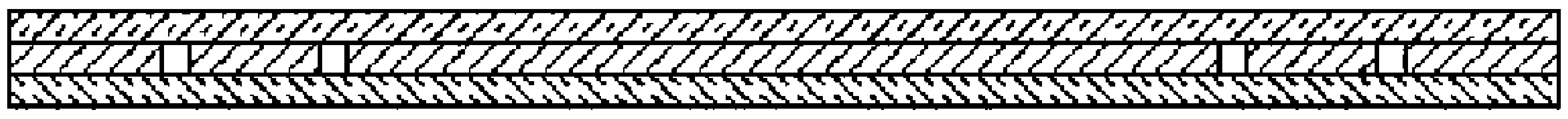

FIG. 21

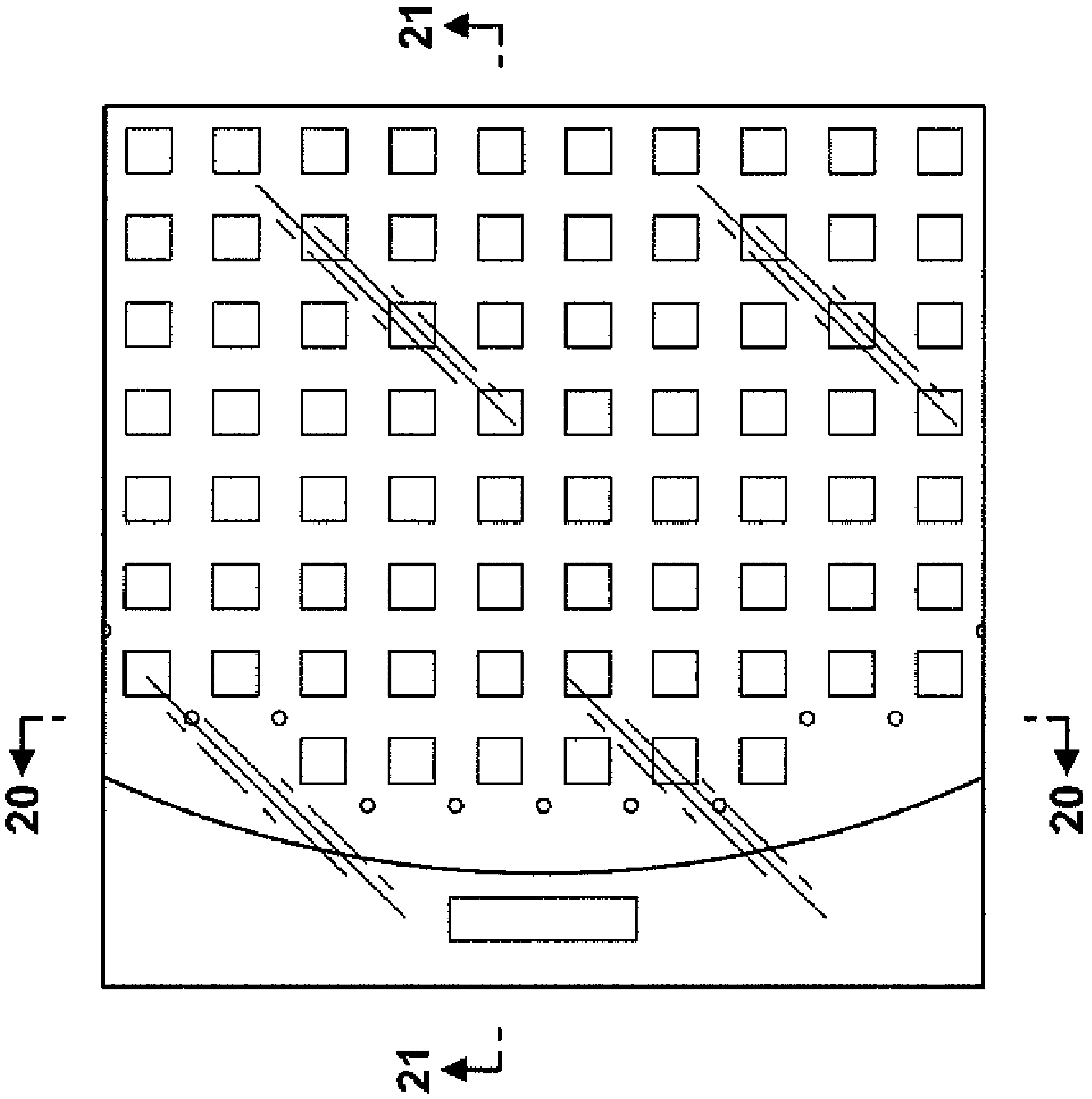

FIG. 19

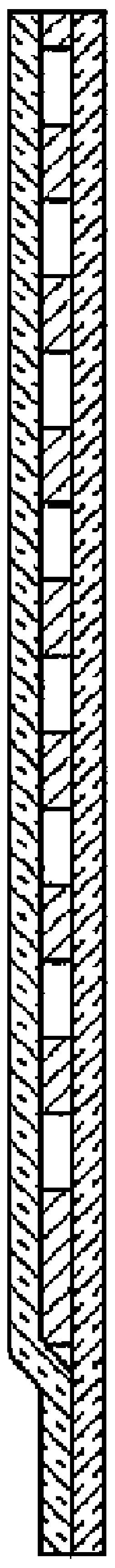

FIG. 20